APPLICAI	BLE STAN	DARD									
RATING	OPERATING TEMPERATURE RANGE OPERATING HUMIDITY RANGE VOLTAGE		-30°C TO + 85°C(NOTE 1) TEN		ТЕМРЕ	STORAGE FEMPERATURE RANGE STORAGE HUMIDITY RANGE VOLTAGE		-10°C TO + 60°C(NOTE 2		2)	
			40% T0 + 80%		HUMID			40% T0 + 70% (NOTE 2) AC 30V			
	CURRENT		AWG 22 TO 26 : 2A AWG 28 : 1A			AWG 22 : AWG 24 TO 28 :		2A 1A			
			AWG 30 : 0.5A			AWG 30 : 0.			. 5A		
			SPEC	IFICA	MOIT	IS					
IT	EM		TEST METHOD				REQU	JIREMENTS	QT	ΙA	
CONSTR GENERAL EX	AMINATION	VISUALLY AND BY MEASURING INSTRUMENT.				ACCORDING TO DRAWING.				ΙX	
MARKING		CONFIRMED VISUALLY.							X	X	
ELECTR	IC CHARA	CTERI	STICS						•		
CONTACT RE	ESISTANCE	100 mA	(DC OR 1000 Hz).		;	30 mΩ M/	₹X.		X	-	
INSULATION RESISTANCE		500 V DC.			•	1000 MΩ MIN.				-	
VOLTAGE PF	ROOF	650 V AC FOR 1 min.			N	NO FLASHOVER OR BREAKDOWN.			X	†-	
MECHAN	IICAL CH	ARACT	ERISTICS		l l					1	
MECHANICAI	L OPERATION	30 TIME	30 TIMES INSERTIONS AND EXTRACTIONS.			 CONTACT RESISTANCE: 30mΩ MAX. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			- X	_	
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.			2	① NO ELECTRICAL DISCONTINUITY OF 1µs. ② NO DAMAGE, CRACK OR LOOSENESS OF			1 1/	_	
SHOCK			490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.				PARTS.				
ENVIROI	NMENTAL		ACTERISTICS						X	1	
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55 \rightarrow 5 TO 35 \rightarrow +85 \rightarrow 5 TO 35 °C TIME 30 \rightarrow 5 TO 15 \rightarrow 30 \rightarrow 5 TO15 min UNDER 5 CYCLES.			min 2	① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 1000MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			Х	_	
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			2	 ↑ CONTACT RESISTANCE: 30mΩ MAX. ⊘ INSULATION RESISTANCE: 500MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 			Х	-	
RESISTANCE TO SOLDERING HEAT A		1) AUTOMATIC SOLDERING (REFLOW) 《REFLOW AREA》 MAX 240°C WITHIN 10 sec. MIN 220°C WITHIN 60sec. 《PREHEATING AREA》 150 TO 180°C 90 TO 120 sec. PUT THROUGH IN REFROW FURNACE TWICE. FEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNEVCTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290±10°C, SOLDERING TIME :3s. NO STRENGTH ON CONTACT.				NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.				_	
SOLDERABIL	LITY		SOLDERED AT SOLDER TEMPERATURE, $230\pm5^{\circ}\text{C}$ FOR IN IMMERSION , DURATION, 3 s.			A NEW UNIFORM COATING OF SOLDER SHALL COVER MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED.			Х	_	
COUN	T D	ESCRIPTI	ON OF REVISIONS		DESIGN	GNED		CHECKED	CHECKED DATE		
1		DIS	DIS-H-001311		AK.MIU		TS.SAKATA		_	06.09.08	
			RATURE RISE BY CURRENT. ON OF LONG TERM STORAGE FOR UNUSED PRODUCTS O, AFTER PCB BOARD, OPERATING TEMPERATURE AND PLIED FOR INTERM STORAGE DURING TRANSPORTATION. O JIS C 5402.			APPROVED CHECKED DESIGNED DRAWN		TS.MIYAZAKI HK.UMEHARA	.UMEHARA 05.02.0 DENPOUYA 05.01.2		
BEFOR	RE PCB ON BOA	ARD , AFTER						IO.DENPOUYA			
								FK.MATSUKI			
Unless otherwise specifid , refer to JIS C 5402. Note QT:Qualification Test AT:Assurance Test X:Applicable Test						RAWING NO. ELC4-306016-					
HS	SPECIFICATION SHEET			-	PART NO.			DF11GZ-*DP-2V(20)			
HI		COS SUSCESSION OF LED			CODE N	VO	CL543		Λ	1/1	
ORM HD0011-					CODE	0L0-10				L''	